



README FILE

ALUMINUM-TRACE PCB

GENERAL INFO

Organization Name:
 Billing Address:
 Shipping Address:
 Purchasing Contact Technical Contact
 Name: Name:
 e-Mail: e-Mail:

PART INFORMATION

Part Number:
 Version.Revision (V.R):
 Description:
 Reason to use AL-Trace PCB: Wire Bond / Superconductivity @ #.# K
 Magnetic Sensitivity (Y/N @ #.# Tesla):
 RF Frequency (Y/N @ #.# Hz):
 Superconductive Vias Required (Y/N):
 Board Size (extends WxH):
 Board Shape: Rectangular / Circular / Irregular

PARAMETERS

OMNI Aluminum-trace PCB Version(Alumifoil/Corefoil):
 Board Layer Count (2-Layer/4-Layer/etc):
 Board Routing (Singles, Tabs, Tooling Pins, V-Score):
 Finished Board Thickness (mils/μm):
 PCB Base Dielectric Material (FR4, Polyimide, etc.):
 Aluminum Thickness (mils/μm):
 Final PCB Surface Metal Finish: Selective Copper on Aluminum / Bare Aluminum
 Solder Mask Layer (Top/Bottom/Both):
 Solder Mask Color:
 Silk Screen Layer (Top/Bottom/Both):
 Silk Screen Color:
 Smallest Trace Width (mils/μm):
 Smallest Space Width (mils/μm):
 Controlled Impedance Design (Y/N):
 Plated Holes (Qty):
 Unplated Holes (Qty):
 Plated Slots (Qty):
 Unplated Slots (Qty):

BACKGROUND INFORMATION

Documentation Tips

The IPC organization developed a standard called "PWB Fabrication Data Quality Rating System" or "IPC-2524", which describes common problems with fabrication data and includes a form that can be used as a checklist when setting up your data output process. This standard is FREE of charge and can be downloaded through their website. Incidentally you can also read about the whole manufacturing process checklists' under the second link: <https://shop.ipc.org/IPC-2524-English-P>
http://www.ipc.org/4.0_Knowledge/4.1_Standards/PCBA-Checklist.pdf

mil = one-thousandth of an inch
 1 oz copper (~35μm or 1.4 mils thick)

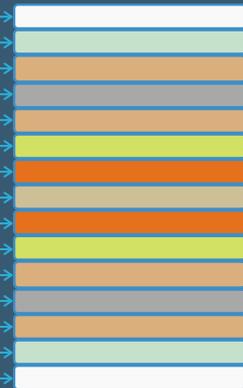
GERBER FILES (ART WORK)

Describe each artwork layer in your Gerber document

File Extension	PCB Layer Description
.TOPCu	Top Copper Layer
.TOPAL	Top Aluminum Layer
Etc	

BUILD SPECIFICATION (PCB STACKUP)

Layer ID	Layer Type	Material	Thickness
SS	Silk Screen	DLP	
SM	Solder Mask	LPI	0.04 mil
L1	Signal	Core 1 - Copper	5 μm
	Signal	Core 1 - Aluminum	30 μm
D1	Dielectric	Prepreg	7.9 mil
	Plain	Copper	0.7 mil
D2	Dielectric	Prepreg	4.2 mil
	Plain	Copper	0.7 mil
D3	Dielectric	Prepreg	7.9 mil
	Signal	Core 2 - Copper	5 μm
L4	Signal	Core 2 - Aluminum	30 μm
	Signal	Core 2 - Copper	5 μm
SM	Solder Mask	LPI	0.04 mil
SS	Silk Screen	DLP	



HOLE LIST

Describe each different hole size in your drill tool table

Size	Qty	Hole Plating and Finish
10 mils	4583	Not plated
31 mils	33	Plated
10 mils	2	Not Plated
Etc		

CRITICAL TOLERANCES & SPECIAL INSTRUCTIONS

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